

Product Change Notification

The information below reflects a change that is being implemented.

Notice Date: 06/18/2007

Product Category: dsPIC

Notification Subject: CCB#745: QUALIFICATION OF NEW LEADFRAME SUPPLIER LGM USING Ag RING PLATED BARE Cu PADDLE FOR THE 80L TQFP 14x14x1.0mm PACKAGE ASSEMBLY AT ATP

Notification Body:

Microchip Part#s Affected:
DSPIC30F5013
DSPIC30F6010A
DSPIC30F6013A
DSPIC30F6014A

Description of Change:
CHANGE IN BILL OF MATERIAL

Impacts to Data Sheet:
NONE

Reason for Change:
TO IMPROVE MANUFACTURABILITY

Estimated Change Implementation Date(s):
August 31, 2007

Markings to Distinguish Revised From Unrevised Devices: (e.g.: Date Code, Device Marking, Ship Container Marking)
TRACEABILITY CODE